

UNR52AVG

Silicon NPN epitaxial planar type

For digital circuits

■ Features

- Costs can be reduced through downsizing of the equipment and reduction of the number of parts.
- SMini type package allowing easy automatic insertion through tape packing

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

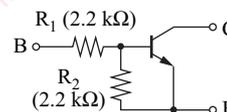
Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V_{CBO}	50	V
Collector-emitter voltage (Base open)	V_{CEO}	50	V
Collector current	I_C	80	mA
Total power dissipation	P_T	150	mW
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

■ Package

- Code
SMini3-F2
- Pin Name
1: Base
2: Emitter
3: Collector

■ Marking Symbol: KP

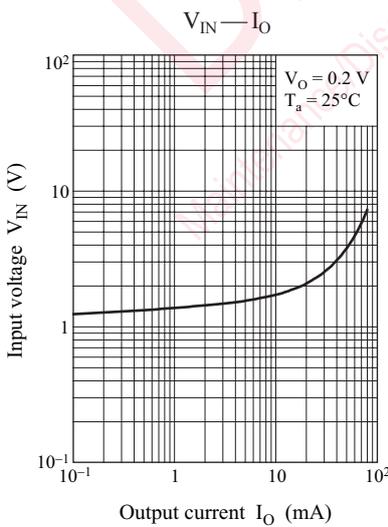
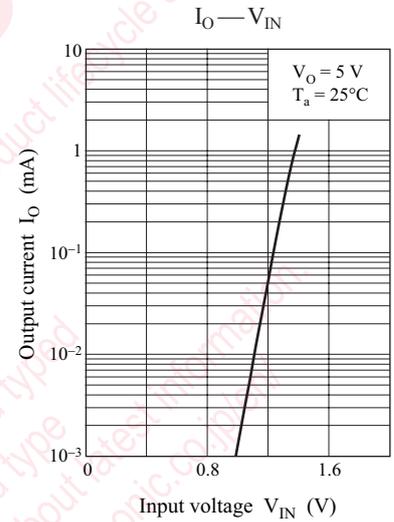
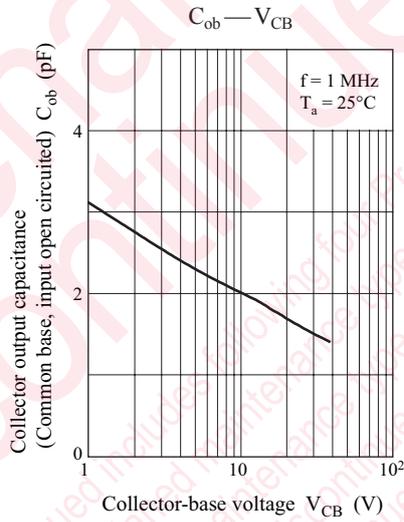
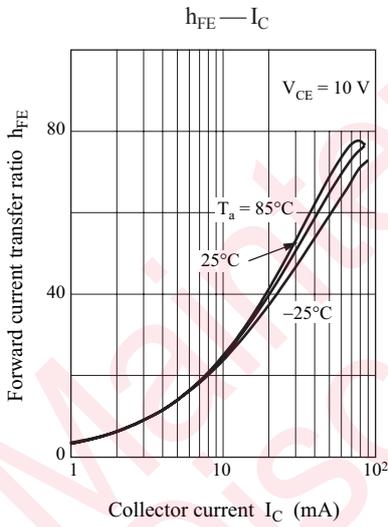
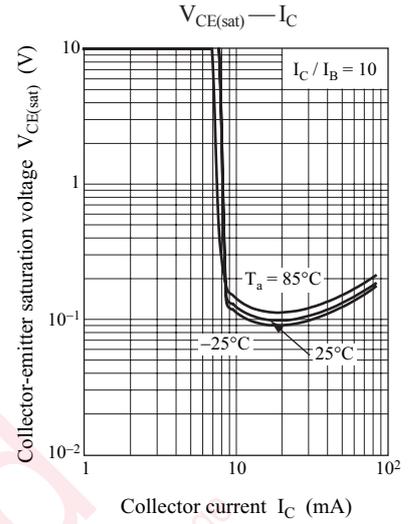
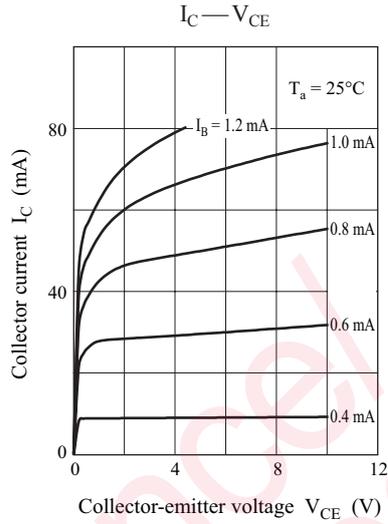
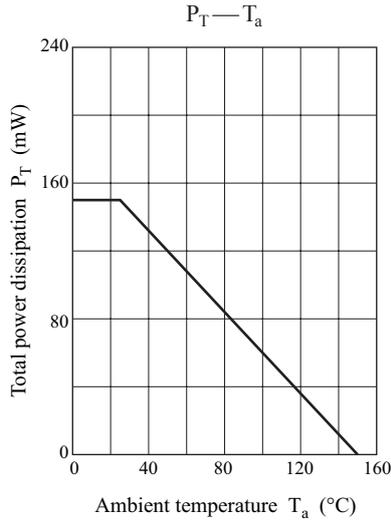
■ Internal Connection



■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

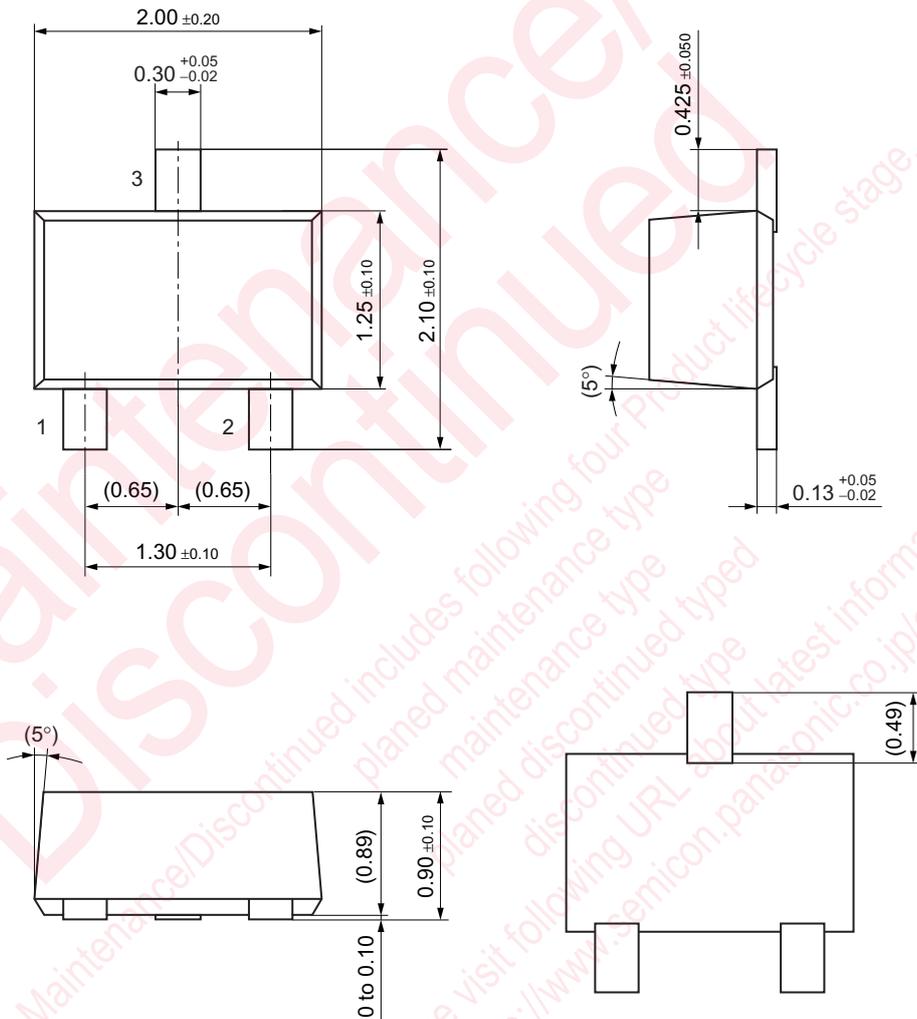
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	V_{CBO}	$I_C = 10 \mu\text{A}, I_E = 0$	50			V
Collector-emitter voltage (Base open)	V_{CEO}	$I_C = 2 \text{mA}, I_B = 0$	50			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = 50 \text{V}, I_E = 0$			0.1	μA
Collector-emitter cutoff current (Base open)	I_{CEO}	$V_{CE} = 50 \text{V}, I_B = 0$			0.5	μA
Emitter-base cutoff current (Collector open)	I_{EBO}	$V_{EB} = 6 \text{V}, I_C = 0$			2.0	mA
Forward current transfer ratio	h_{FE}	$V_{CE} = 10 \text{V}, I_C = 5 \text{mA}$	6	20		—
Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_C = 10 \text{mA}, I_B = 1.5 \text{mA}$			0.25	V
Output voltage high-level	V_{OH}	$V_{CC} = 5 \text{V}, V_B = 0.5 \text{V}, R_L = 1 \text{k}\Omega$	4.9			V
Output voltage low-level	V_{OL}	$V_{CC} = 5 \text{V}, V_B = 2.5 \text{V}, R_L = 1 \text{k}\Omega$			0.2	V
Input resistance	R_1		-30%	2.2	+30%	$\text{k}\Omega$
Resistance ratio	R_1 / R_2			1.0		—
Transition frequency	f_T	$V_{CB} = 10 \text{V}, I_E = -2 \text{mA}, f = 200 \text{MHz}$		150		MHz

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.



SMini3-F2

Unit: mm



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